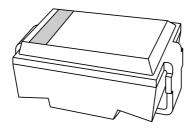
## **DISCRETE SEMICONDUCTORS**

## DATA SHEET



# **BZG03 series**Voltage regulator diodes

Product specification Supersedes data of 1996 Jun 07 2002 Jul 04





## Voltage regulator diodes

## **BZG03** series

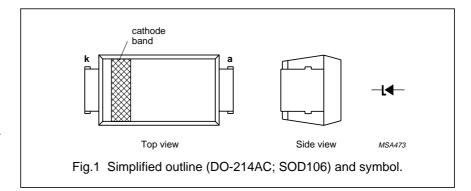
#### **FEATURES**

- · Glass passivated
- High maximum operating temperature
- Low leakage current
- · Excellent stability
- UL 94V-O classified plastic package
- Zener working voltage range: 10 to 270 V for 35 types
- Supplied in 12 mm embossed tape.

#### **DESCRIPTION**

DO-214AC surface mountable package with glass passivated chip.

The well-defined void-free case is of a transfer-moulded thermo-setting plastic.



#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
P <sub>tot</sub>	total power dissipation	T <sub>tp</sub> = 100 °C; see Fig.2	_	3.00	W
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 50 °C; see Fig.2; device mounted on an Al <sub>2</sub> O <sub>3</sub> PCB (see Fig.5)	_	1.25	W
P <sub>ZSM</sub>	non-repetitive peak reverse power dissipation	$t_p$ = 100 μs; square pulse; $T_j$ = 25 °C prior to surge; see Fig.3	_	600	W
T <sub>stg</sub>	storage temperature		-65	+175	°C
Tj	junction temperature		-65	+175	°C

## Voltage regulator diodes

BZG03 series

## **ELECTRICAL CHARACTERISTICS**

## **Total series**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
$V_{F}$	forward voltage	I <sub>F</sub> = 0.5 A; see Fig.4	1.2	V

## Per type

 $T_j = 25$  °C unless otherwise specified.

TYPE No.	WORI	WORKING VOLTAGE			DIFFERENTIAL RESISTANCE		RATURE	TEST CURRENT		URRENT at VOLTAGE		
SUFFIX	,	/ <sub>Z</sub> (V) at I	Z	r <sub>dif</sub> (Ω	) at Iz	S <sub>Z</sub> (%/K) at I <sub>Z</sub>		at I <sub>Z</sub> S <sub>Z</sub> (%/K) at I <sub>Z</sub>			<b>I</b> <sub>R</sub> (μ <b>A</b> )	
(1)	MIN.	NOM.	MAX.	TYP.	MAX.	MIN.	MAX.	I <sub>Z</sub> (mA)	MAX.	V <sub>R</sub> (V)		
C10	9.4	10	10.6	2	4	0.05	0.09	50	7	7.5		
C11	10.4	11	11.6	4	7	0.05	0.10	50	4	8.2		
C12	11.4	12	12.7	4	7	0.05	0.10	50	3	9.1		
C13	12.4	13	14.1	5	10	0.05	0.10	50	2	10		
C15	13.8	15	15.6	5	10	0.05	0.10	50	1	11		
C16	15.3	16	17.1	6	15	0.06	0.11	25	1	12		
C18	16.8	18	19.1	6	15	0.06	0.11	25	1	13		
C20	18.8	20	21.2	6	15	0.06	0.11	25	1	15		
C22	20.8	22	23.3	6	15	0.06	0.11	25	1	16		
C24	22.8	24	25.6	7	15	0.06	0.11	25	1	18		
C27	25.1	27	28.9	7	15	0.06	0.11	25	1	20		
C30	28	30	32	8	15	0.06	0.11	25	1	22		
C33	31	33	35	8	15	0.06	0.11	25	1	24		
C36	34	36	38	21	40	0.06	0.11	10	1	27		
C39	37	39	41	21	40	0.06	0.11	10	1	30		
C43	40	43	46	24	45	0.07	0.12	10	1	33		
C47	44	47	50	24	45	0.07	0.12	10	1	36		
C51	48	51	54	25	60	0.07	0.12	10	1	39		
C56	52	56	60	25	60	0.07	0.12	10	1	43		
C62	58	62	66	25	80	0.08	0.13	10	1	47		
C68	64	68	72	25	80	0.08	0.13	10	1	51		
C75	70	75	79	30	100	0.08	0.13	10	1	56		
C82	77	82	87	30	100	0.08	0.13	10	1	62		
C91	85	91	96	60	200	0.09	0.13	5	1	68		
C100	94	100	106	60	200	0.09	0.13	5	1	75		
C110	104	110	116	80	250	0.09	0.13	5	1	82		
C120	114	120	127	80	250	0.09	0.13	5	1	91		
C130	124	130	141	110	300	0.09	0.13	5	1	100		
C150	138	150	156	130	300	0.09	0.13	5	1	110		

## Voltage regulator diodes

BZG03 series

TYPE No.	WORKING VOLTAGE		DIFFERENTIAL RESISTANCE		TEMPERATURE COEFFICIENT		TEST CURRENT	REVERSE C	URRENT at VOLTAGE	
SUFFIX	V <sub>Z</sub> (V) at I <sub>Z</sub>		r <sub>dif</sub> (Ω) at I <sub>Z</sub>		S <sub>Z</sub> (%/K) at I <sub>Z</sub>		I (m A)	I <sub>R</sub> (μ <b>A</b> )	V 00	
(1)	MIN.	NOM.	MAX.	TYP.	MAX.	MIN.	MAX.	I <sub>Z</sub> (mA)	MAX.	V <sub>R</sub> (V)
C160	153	160	171	150	350	0.09	0.13	5	1	120
C180	168	180	191	180	400	0.09	0.13	5	1	130
C200	188	200	212	200	500	0.09	0.13	5	1	150
C220	208	220	233	350	750	0.09	0.13	2	1	160
C240	228	240	256	400	850	0.09	0.13	2	1	180
C270	251	270	289	450	1000	0.09	0.13	2	1	200

## Note

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point		25	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	100	K/W
		note 2	150	K/W

## **Notes**

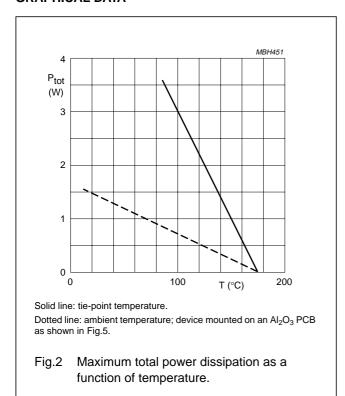
- 1. Device mounted on an  $Al_2O_3$  printed-circuit board, 0.7 mm thick; thickness of Cu-layer  $\geq$ 35  $\mu$ m, see Fig.5.
- 2. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer  $\geq$ 40  $\mu$ m, see Fig.5. For more information please refer to the "General Part of associated Handbook".

<sup>1.</sup> To complete the type number the suffix is added to the basic type number, e.g. BZG03-C130.

## Voltage regulator diodes

## BZG03 series

## **GRAPHICAL DATA**



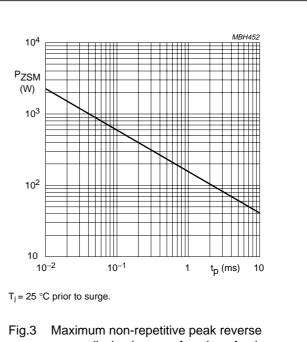
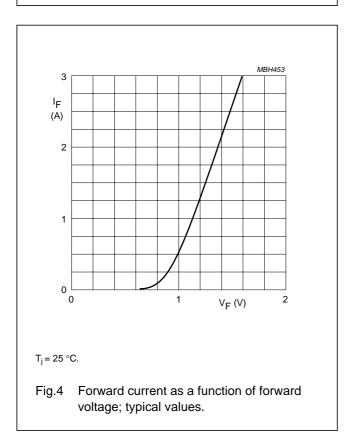
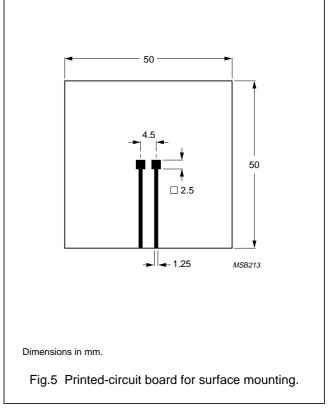


Fig.3 Maximum non-repetitive peak reverse power dissipation as a function of pulse duration (square pulse).





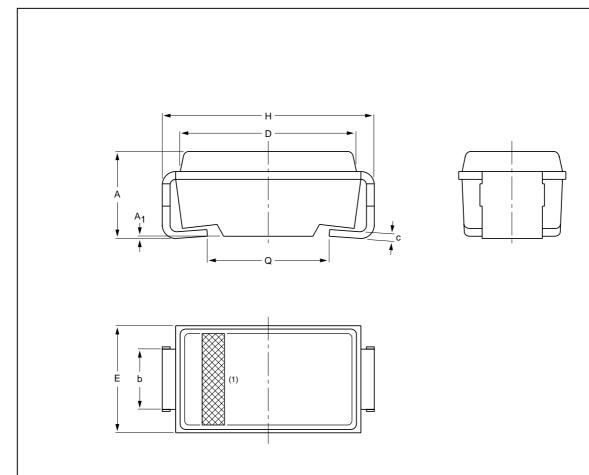
## Voltage regulator diodes

BZG03 series

## **PACKAGE OUTLINE**

Transfer-moulded thermo-setting plastic small rectangular surface mounted package; 2 connectors

SOD106





## **DIMENSIONS** (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	С	D	E	н	Q
mm	2.3 2.0	0.05	1.6 1.4	0.2	4.5 4.3	2.8 2.4	5.5 5.1	3.3 2.7

#### Note

1. The marking band indicates the cathode.

OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOD106		DO-214AC				97-06-09

## Voltage regulator diodes

BZG03 series

#### **DATA SHEET STATUS**

DATA SHEET STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
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